

1.Features

- $V_{DS} = -30V$
- $I_D = -13.5A$
- $R_{DS(ON)} = 11m\Omega (V_{GS} = -10V)$
- $R_{DS(ON)} = 15m\Omega (V_{GS} = -4.5V)$

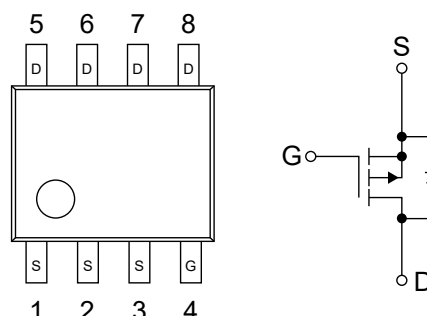
2.Applications

- Load Switch
- Notebook Adaptor Switch

3.Pinning information

Pin	Symbol	Description
4	G	GATE
1,2,3	S	SOURCE
5,6,7,8	D	DRAIN

SOP-8



4.Absolute Maximum Ratings $T_A = 25^\circ C$ unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ($T_J = 150^\circ C$)	$T_C = 25^\circ C$	I_D	-13.5	A
	$T_C = 70^\circ C$		-11.9	
	$T_A = 25^\circ C$		-10.9 ^{a,b}	
	$T_A = 70^\circ C$		-8.6 ^{a,b}	
Pulsed Drain Current		I_{DM}	-50	
Continuous Source-Drain Diode Current	$T_C = 25^\circ C$	I_S	-4.1	
	$T_A = 25^\circ C$		-2.2 ^{a,b}	
Avalanche Current	L = 0.1 mH	I_{AS}	-20	mJ
Single-Pulse Avalanche Energy		E_{AS}	20	



Maximum Power Dissipation	$T_C=25^{\circ}\text{C}$	P_D	5	W
	$T_C=70^{\circ}\text{C}$		3.2	
	$T_A=25^{\circ}\text{C}$		2.7 ^{a,b}	
	$T_A=70^{\circ}\text{C}$		1.7 ^{a,b}	
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	$^{\circ}\text{C}$

5.Thermal resist ance rating

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^{a,c}	$t \leq 10\text{s}$	R_{thJA}	38	46	$^{\circ}\text{C/W}$
Maximum Junction-to-Foot (Drain)	Steady-State	R_{thJF}	20	25	$^{\circ}\text{C/W}$

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. $t=10\text{s}$.
- c. Maximum under Steady State conditions is 85 $^{\circ}\text{C/W}$.
- d. Based on $T_C=25^{\circ}\text{C}$.



6.Specifications (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{DS} =0V, I _D =-250μA	-30			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D =-250μA		-34		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			5.3		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.4		-2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±25V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V			-1	μA
		V _{DS} =-30V, V _{GS} =0V, T _J =55°C			-5	
On-State Drain Current ^a	I _{D(ON)}	V _{DS} ≥10V, V _{GS} =-10V	-30			A
Drain-Source On-State Resistance ^a	R _{DS(ON)}	V _{GS} =-10V, I _D =-10A		11		mΩ
		V _{GS} =-4.5V, I _D =-8A		15		
Forward Transconductance ^a	g _{FS}	V _{DS} =-10V, I _D =-10A		28		S
Dynamic^b						
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V, f=1MHz		2550		pF
Output Capacitance	C _{oss}			455		
Reverse Transfer Capacitance	C _{rss}			390		
Total Gate Charge	Q _g	V _{DS} =-15V, V _{GS} =-10V I _D =-10A		57	86	nC
				29.5	45	
Gate Source Charge	Q _{gs}	V _{DS} =-15V, V _{GS} =-4.5V		8		
Gate Drain Charge	Q _{gd}	I _D =-10A		22		
Gate Resistance	R _g	f=1MHz	0.5	2.2	4.4	Ω
Turn-On DelayTime	t _{D(on)}	V _{DD} =-15V, R _L =1.5Ω I _D =-10A, V _{GEN} =-10V R _g =1Ω		13	25	ns
Rise Time	t _r			12	24	
Turn-Off DelayTime	t _{D(off)}			40	70	
Fall Time	t _f			9	18	



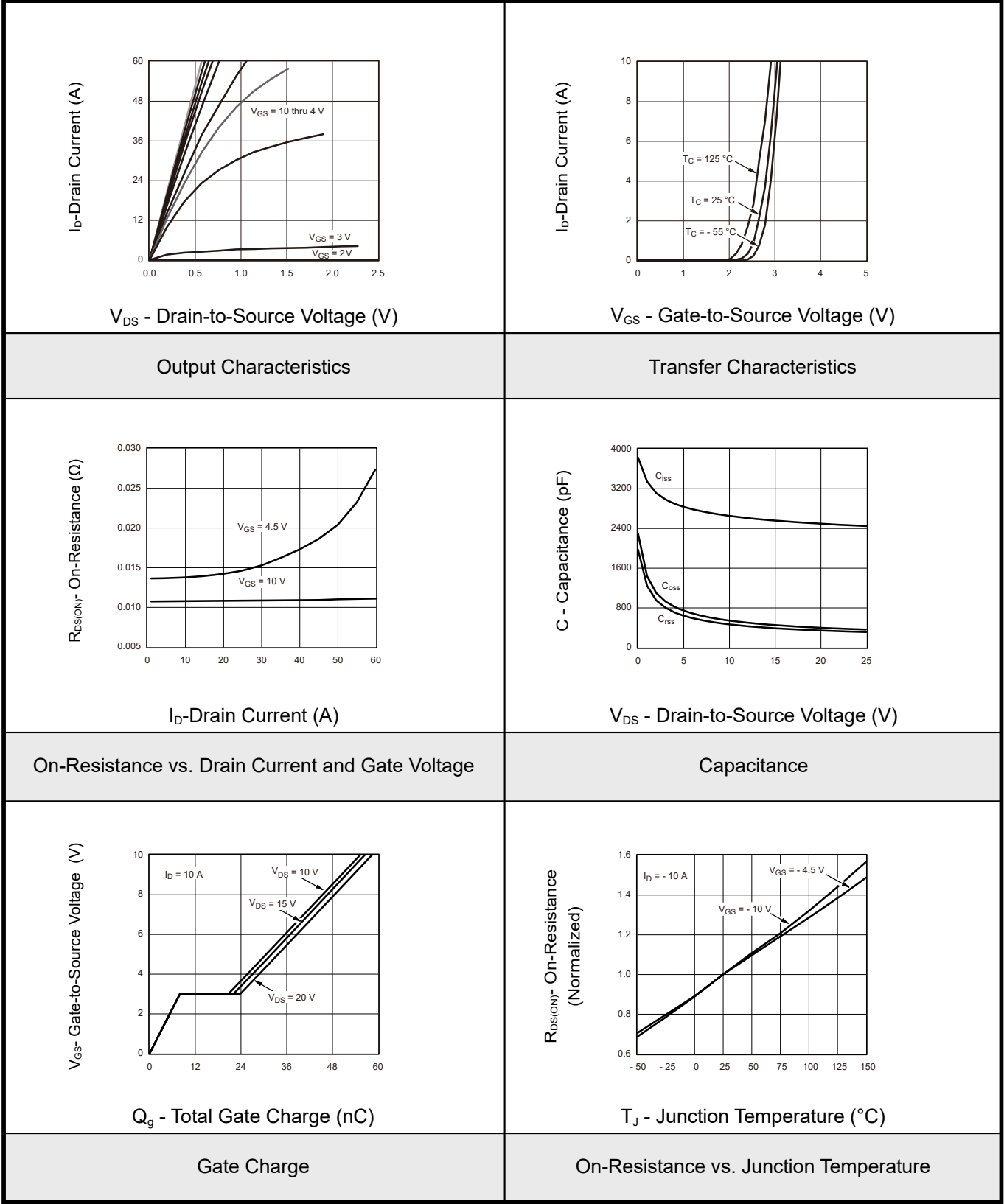
Turn-On Delay Time	$t_{D(on)}$	$V_{DD}=-15V, R_L=1.5\Omega$ $I_D=\infty-10V, V_{GEN}=-4.5V$ $R_g=1\Omega$		48	80	ns
Rise Time	t_r			92	160	ns
Turn-Off Delay Time	$t_{D(off)}$			34	60	ns
Fall Time	t_f			19	35	ns
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	$T_C=25^{\circ}C$			-4.1	A
Pulse Diode Forward Current	I_{SM}				-60	A
Body Diode Voltage	V_{SD}	$I_S=-3A, V_{GS}=0V$		-0.75	-1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F=-10A, dI/dt=100A/\mu s$ $T_J=25^{\circ}C$		27	45	ns
Body Diode Reverse Recovery Charge	Q_{rr}			16	27	nC
Reverse Recovery Fall Time	t_a			12		ns
Reverse Recovery Rise Time	t_b			15		ns

Notes:

- a. Pulse test; pulse width $\leq 300 \mu s$, duty cycle $\leq 2 \%$.
- b. Guaranteed by design, not subject to production testing.

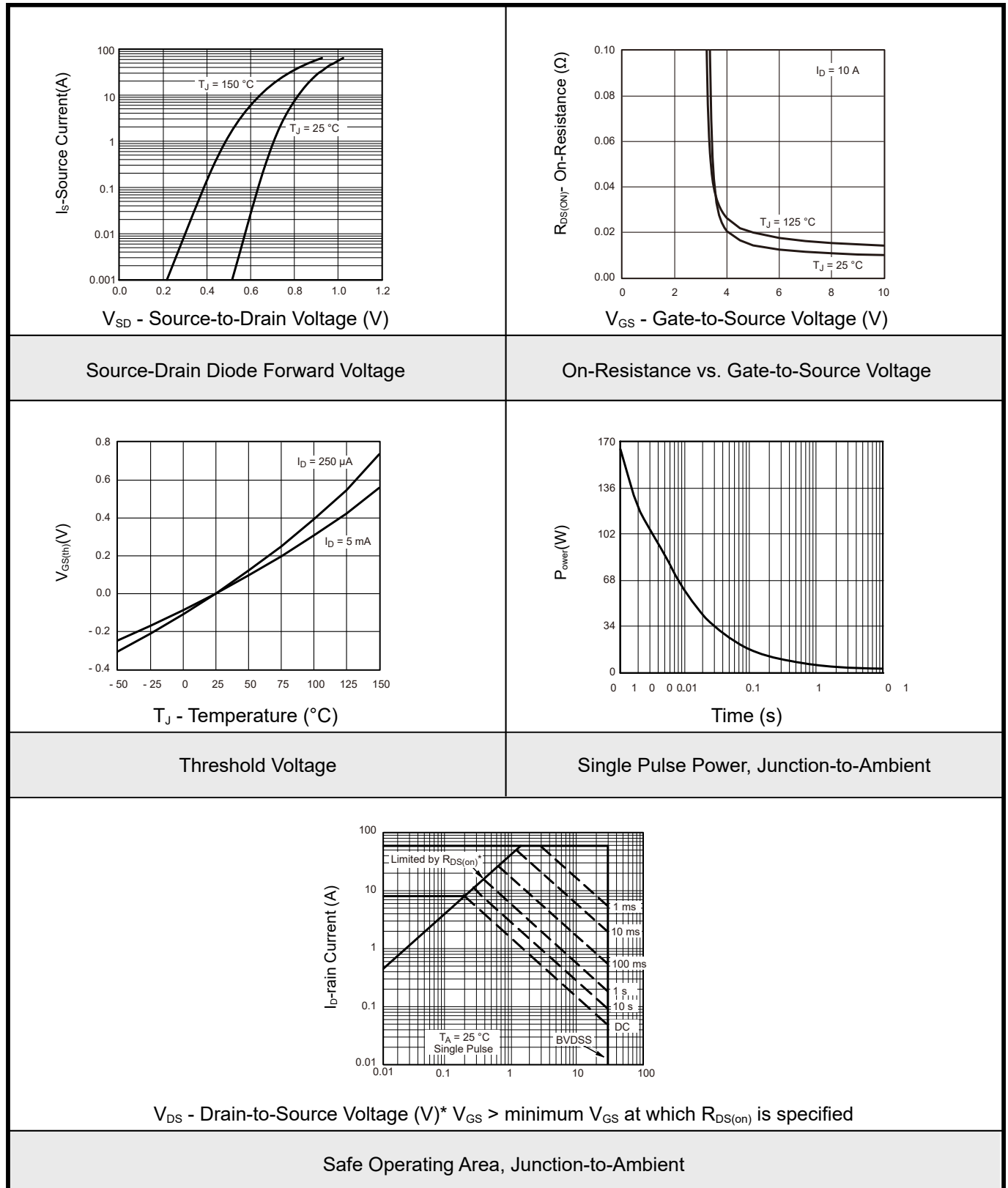


7.1 Typical characteristic 25 °C, unless otherwise noted



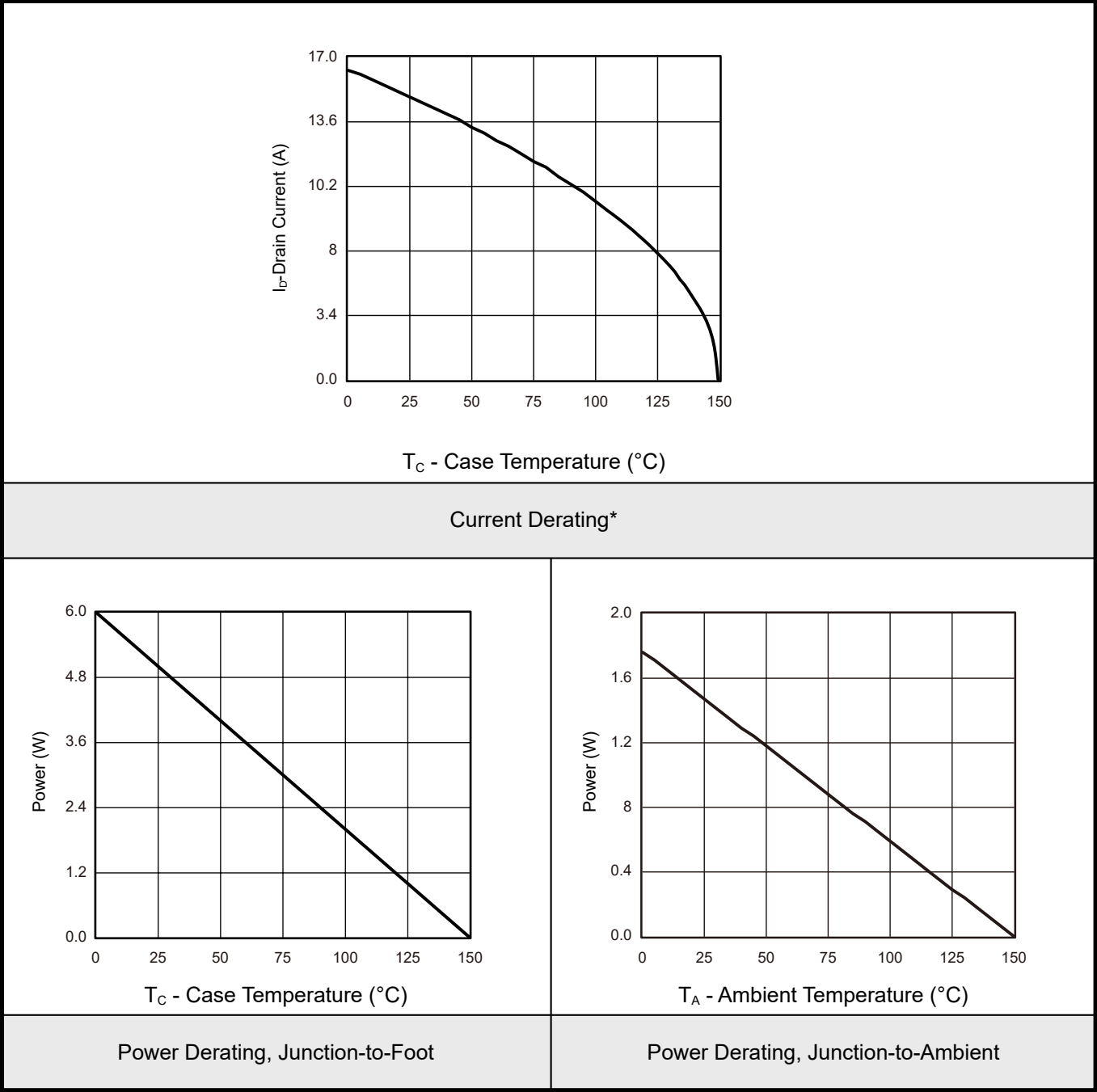


7.2 Typical characteristic 25 °C, unless otherwise noted





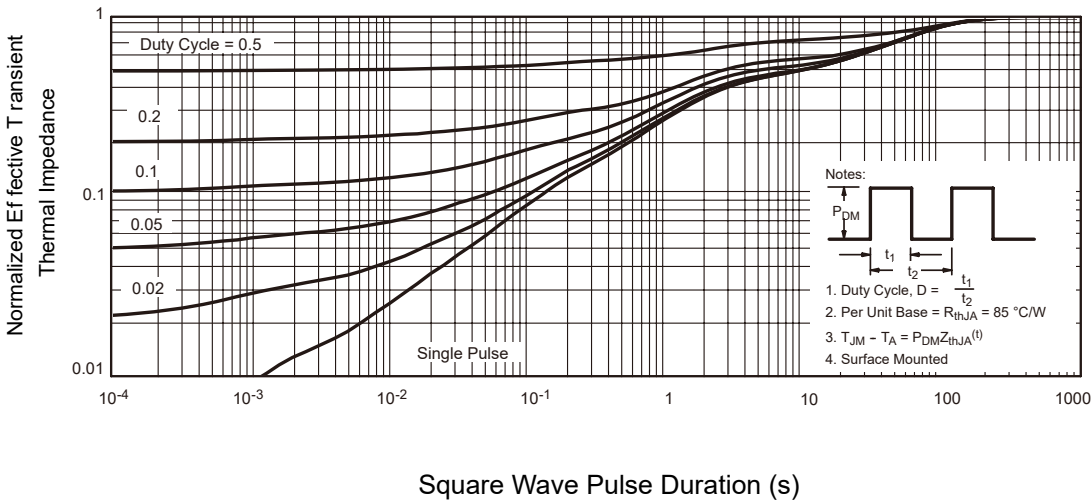
7.3Typical characteristic 25 °C, unless otherwise noted



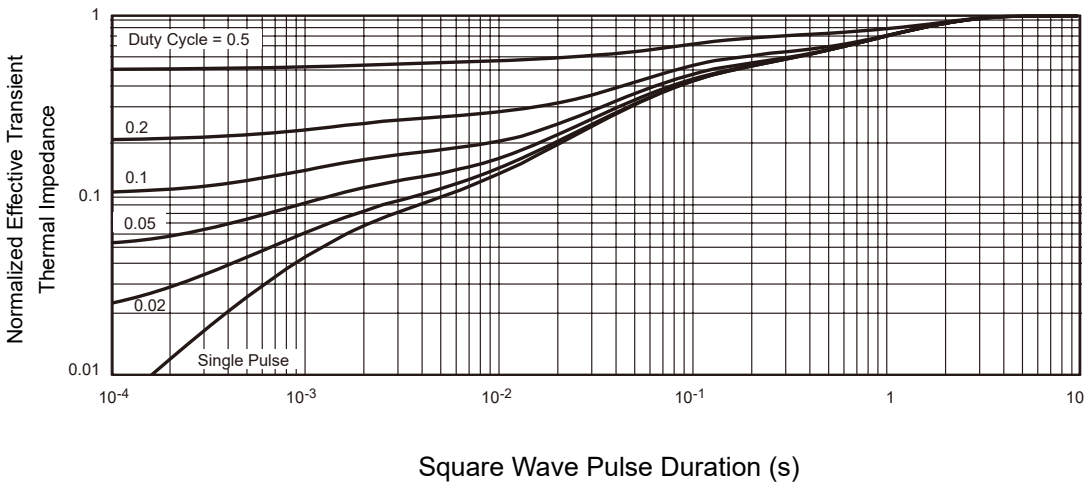
* The power dissipation P_D is based on $T_{J(max)} = 150\text{ }^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in settling the upperdissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



7.4Typical characteristic 25 °C, unless otherwise noted



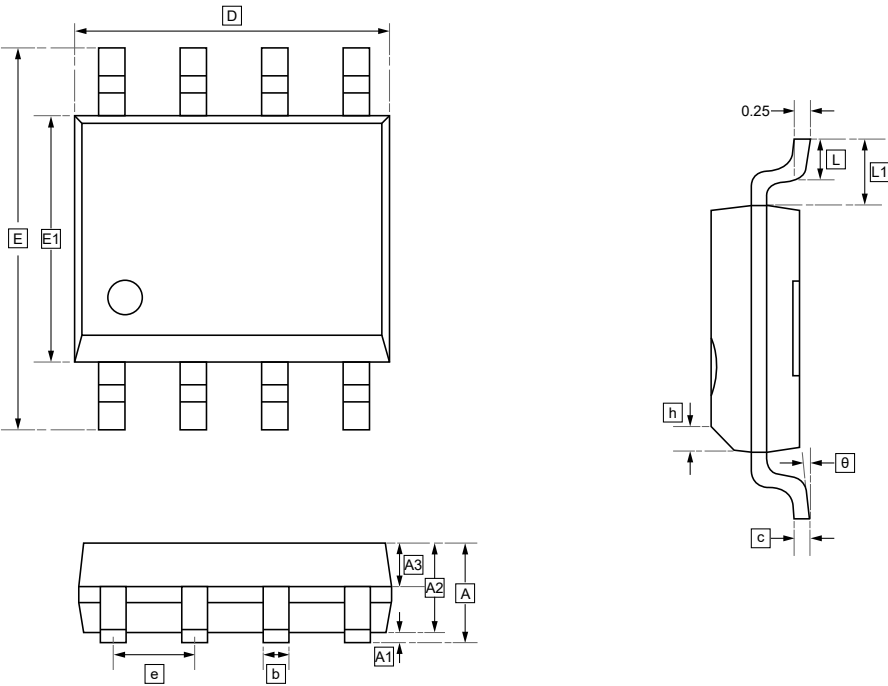
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



8.SOP-8 Package Outline Dimensions



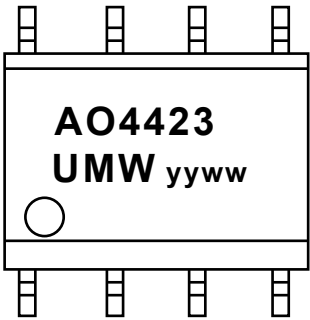
DIMENSIONS (mm are the original dimensions)

Symbol	A	A1	A2	A3	b	c	D	E	E1	e	h	L
Min	-	0.05	1.30	0.60	0.39	0.20	4.80	5.80	3.80	1.24	0.30	0.50
Max	1.75	0.20	1.50	0.70	0.47	0.24	5.00	6.20	4.00	1.30	0.50	0.80

Symbol	L1	θ
Min	1.00	0°
Max	1.10	8°



9.Ordering information



yy: Year Code
ww: Week Code

Order Code	Package	Base QTY	Delivery Mode
UMW AO4423	SOP-8	3000	Tape and reel



10.Disclaimer

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